

Abstract

Electronic component, and a panel for its production

The invention relates to an electronic component (1) having stacked semiconductor chips (3, 4), and to a panel (23) for production of the component (1). For this purpose, the stack (2) has a flat conductor structure (8) with a chip island (9) on which a stacked semiconductor chip (4) is arranged, while a first semiconductor chip (3) is located underneath it. The chip island (9) is surrounded by flat conductors (10) which have contact pillars (11). These contact pillars (11) have pillar contact pads (13) which, together with the active upper face (5) of the first semiconductor chip (3) and the upper face areas (14) of a plastic encapsulation compound (15) form a coplanar overall upper face (16).

(Figure 1)